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Accelerated switchover to lead-free solder in response to Europe's RoHS directive

~ Packaging ~

Since July 1, 2006, the use of products containing materials specified by RoHS is prohibited in EU Member States. In semiconductor packages, usage of lead-tin alloy which was used as a solder material for printed circuit boards is prohibited, and the development of the lead-free solder material advanced. The lead content is specified to be 1000 ppb (0.1 wt%) or less. The melting point of the lead-free solder material is higher by about 30 degrees than that of the lead-tin solder material, that required to use package materials that can withstand higher temperature.

RoHS:Restriction of Hazardous Substances

